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PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Kenji HORI

Group Art Unit: 2873

Application No.: 10/665,568

Examiner: M. HASAN

Filed: September 22, 2003

Docket No.: 111608.01

For: OPTICAL COMPONENT THICKNESS ADJUSTMENT METHOD, OPTICAL  
COMPONENT, AND POSITION ADJUSTMENT METHOD FOR OPTICAL  
COMPONENT

REQUEST FOR RECONSIDERATION

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

In reply to the December 14, 2005 Office Action, reconsideration of the rejection is respectfully requested in light of the following remarks.

Claims 5, 6, 8, 9 and 11 are currently pending

The Office Action rejects claims 5, 6, 8 and 9 under 35. U.S.C. §102(b) over U.S.

Patent No. 5,479,049 to Aoki et al. (Aoki). This rejection is respectfully traversed.

Claim 5 recites, *inter alia*, etching a surface of a manufactured lens to reduce the optical thickness when the optical thickness of the manufactured lens is greater than a target optical thickness.

The Office Action alleges that col. 5, lines 40-44 of Aoki teach this feature.

Applicants respectfully disagree.

The cited portion of Aoki teaches that when the adhesion between the first transparent resin layer 12 and the micro lens 11 is weak, the adhesion between the first transparent resin